



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 5478**  
Hidenori HASEGAWA : **Attorney Docket No. 2004\_0096A**  
Serial No. 10/762,451 : **Group Art Unit 2823**  
Filed January 23, 2004 : **Examiner Fernando Toledo**

SEMICONDUCTOR DEVICE AND  
FABRICATION METHOD THEREOF

**RESPONSE UNDER 37. CFR 1.116**  
**EXPEDITED PROCEDURE**  
**EXAMINING GROUP 2823**

**REQUEST FOR RECONSIDERATION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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1/7 7/26/06*

Sir:

In view of the following remarks, reconsideration of the rejections contained in the Office Action of March 20, 2006 is respectfully requested.

Claims 8-17, including independent claims 8, 11, and 14, are presently pending and were treated in the outstanding Office Action. In particular, the Examiner rejected all the pending claims as being anticipated by the Minamio reference (US Application Publication 2003/0015775). In other words, the Examiner applied the same prior art reference applied in the previous Office Action of July 26, 2005. However, the Examiner's rejections are traversed. For the reasons discussed below, it is respectfully submitted that claims 8-17 are clearly patentable over the prior art of record.

In a conventional semiconductor device, a leadframe needs to be prepared with a particular shape so as to match a specific semiconductor chip. At least partly due to this inconvenience, such a semiconductor device cannot be manufactured using an efficient sequence of processing steps. As a result, the necessary time required to fabricate the semiconductor device is increased (see page 2, lines 4-17 of the original specification).